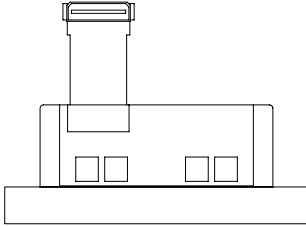


**WIREBONDING CHECKLIST FOR CMS TEC HYBRIDS**  
**FOR 8060 WIREBONDER**

**Program:**       TEC4CHP or TEC6CHP

**Part Orientation:**



***1. Pitch Adapter to Chip Bonds***

**Lead Reference System (L): Pitch Adapter**

**Die Reference System (U): Chip**

operator point 1:  
1. pad, bottom left  
corner

operator point 2:  
63. pad, bottom right  
corner



operator point 1:  
1. pad, top left  
corner

operator point 2:  
63. pad, top right  
corner



**First Bond: Pitch Adapter**

**Second Bond: Chip**

Bond time: 20 ms

Bond time: 20 ms

USG Current: 55 mA

USG Current: 50 mA

Force: 20

Force: 35

Tip: 20 mils

Tip: 20 mils

**Loop Parameters:**

**Tail Parameters:**

Shape: square

Feed: 75

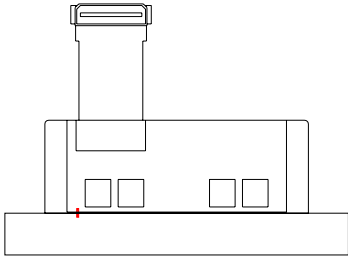
Loop height: short bonds 15 mils, long bonds 25 mils

Clear height: short bonds 100 mils, long bonds 100 mils

clamp close at loop

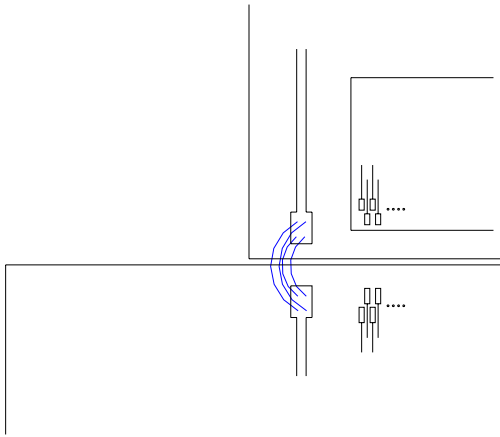
## 2. Hybrid Bias Bonds

### Bias Bonds Location:



### Pitch Adapter to Gold Pad on Hybrid:

Place 4 bonds, 2 short, 2 long



### First Bond: Pitch Adapter

Bond time: 20ms

USG Current: 55 mA

Force: 20

Tip: 20 mils

### Loop Parameters:

Shape: square

Loop height: short bonds 30 mils, long bonds 40 mils

Clamp close at loop

### Second Bond: Gold

Bond time: 35 ms

USG Current: 65 mA

Force: 25

Tip: 20 mils

### Tail Parameters:

Feed: 75